

Heterogeneous Technology Alliance



**The photonic sensing and
integration platform of the
HTA**

Christian Bosshard & the
HTA Photonics Platform
Team

Noordwijk, October 15, 2012

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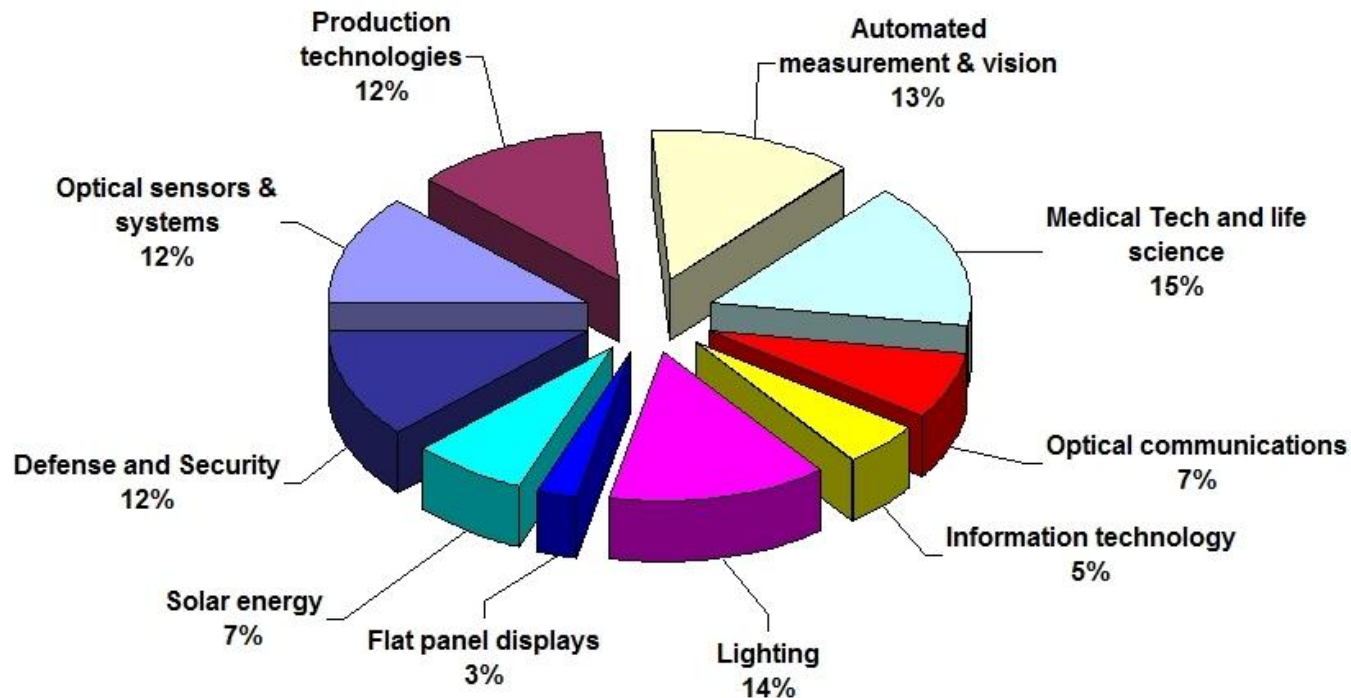
The Heterogeneous Technology Alliance HTA

Photonics – benefits for Europe

- Photonics accepted as a EU key enabling technology
- Photonics components and systems
 - Development and integration
 - Automation whenever needed
 - (Small) series production
 - Testing of components
- Benefit for Europe:
 - Today assembly of optical systems is moving to Extreme East
 - Miniaturization and integration means automation:
 - Less dependence on human assembly
 - Possibility of relocating/regrowing industry back to Europe

European Photonics Production by sector, 2010
Total = 62.4 Billion euros

EPIC estimates that 350 000 are employed in the Photonics Sector in the Europe zone.



Why HTA ?

Because Photonics comprises many aspects

- From the device to the architecture
- Design for assembly
- Several types of devices involved:
 - Lasers, detectors, modulators, multiplexing components, etc
- Several type of materials involved:
 - Si (CMOS), III-V (lasers), LiNbO₃ (modulators), Glass, etc...
 - With different levels of trade-offs in terms of cost, complexity and performances
- Optical SiP (O-SiP) versus Optical SoC (O-SoC)

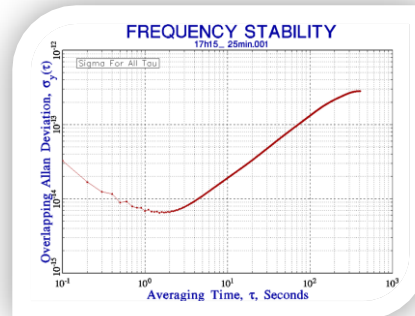
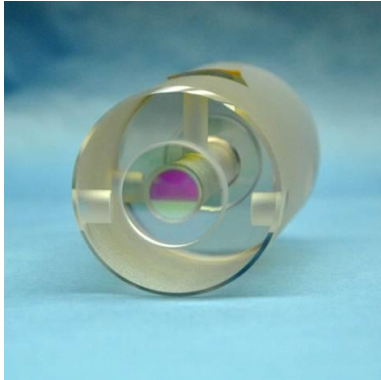
The targeted Photonics platform will be available for Space applications

Combine a variety of HTA technologies to address the above challenges

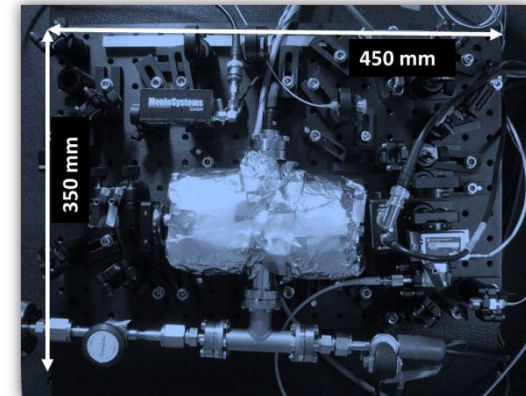
- Light sources
 - Light processing (fiber, waveguides, micro-(opto)-electromechanical systems (MOEMS),...)
 - Light filtering
 - Light detection
 - Assembly and integration
 - The next layer
- Enable photonics to deliver more functionality without adding complexity for the user

Stabilized cw-lasers: Industry-fit high performance & miniaturization

High Performance: Pound-Drever-Hall stabilization in optical cavity.

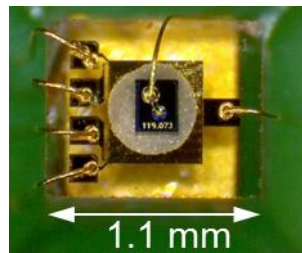
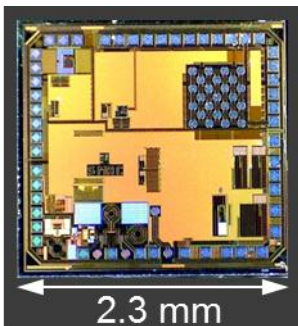


Achieved @ CSEM:
Robust 1 Hz linewidth @ 1 s



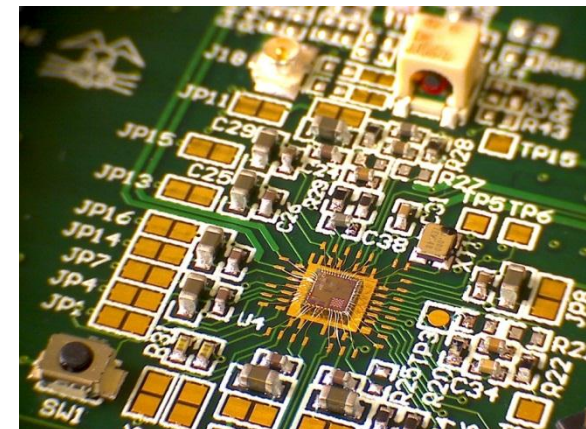
Going towards:
Smaller, lighter, more robust, space compatible

Miniaturization: Frequency lock through synchronized detection



Achieved @ CSEM:
ASIC-controlled VCSEL wavelength stabilization on Rb absorption line.

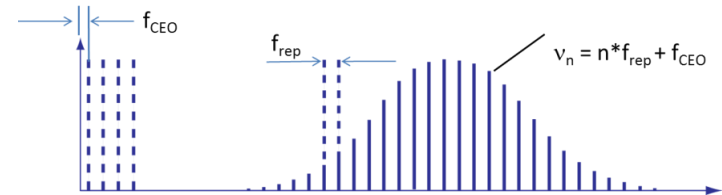
Going towards:
Lower power, higher integration, other laser types (DFB) and molecular absorption lines



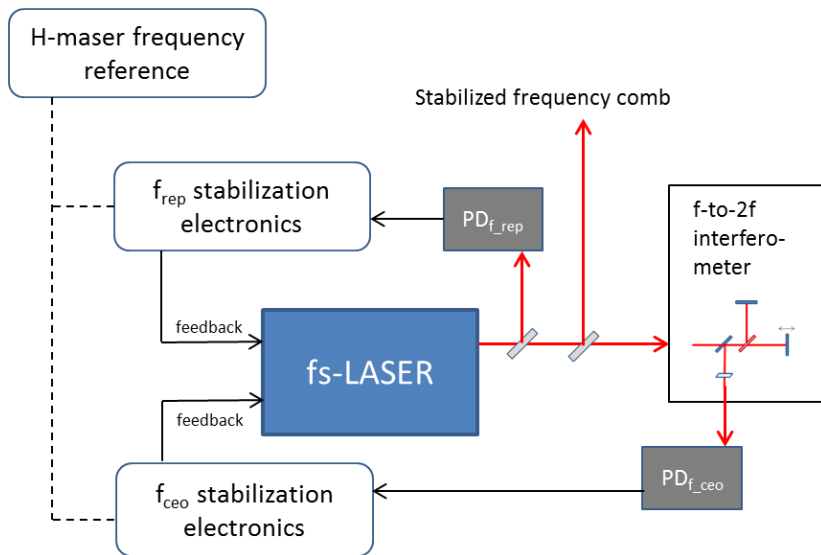
Stabilized optical frequency comb (fs laser)

Applications:

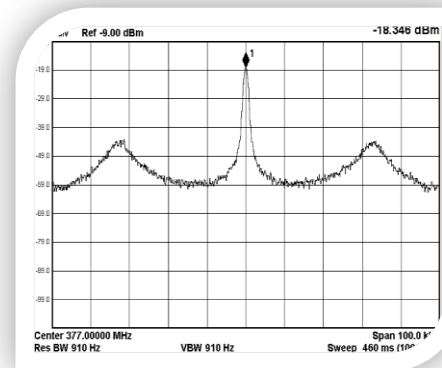
- Fast high resolution optical spectroscopy
- Distance measurement
- Time and frequency transfer
- Low phase-noise microwave generation



Stabilization setup

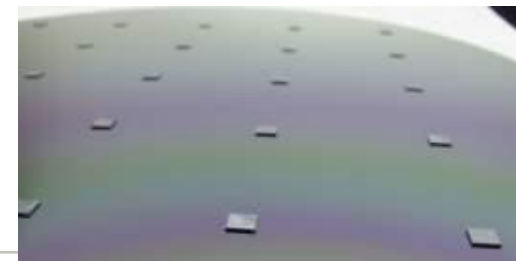
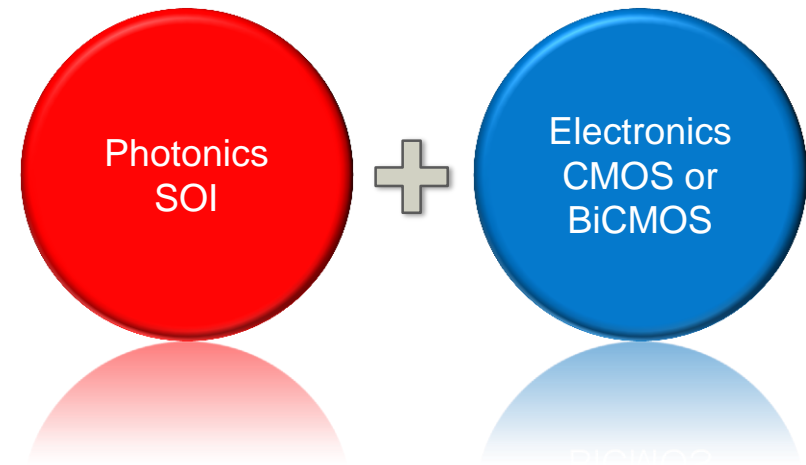


supercontinuum generation



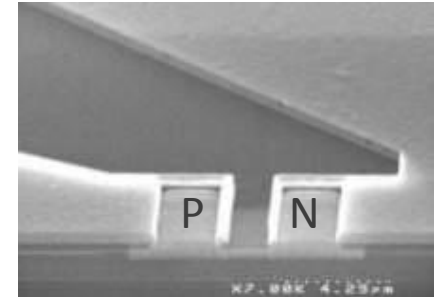
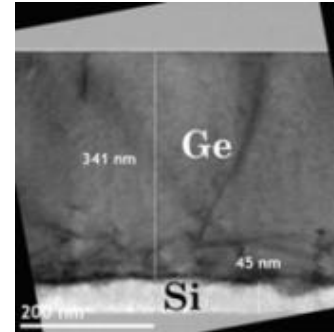
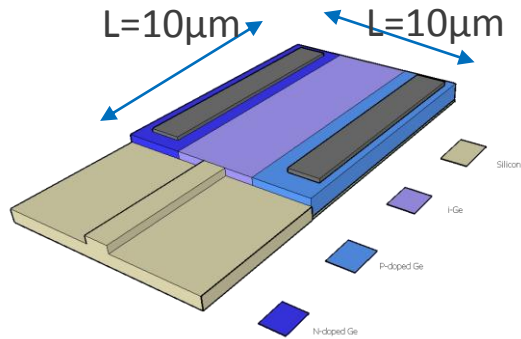
state-of-the-art stabilized carrier-envelope offset frequency

- Our objectives:
 - Build a complete technology platform (design, process, test, packaging) for photonics /electronics integration
- Our approach
 - Photonics/electronics 3D integration
→ yield, performance, cost
 - Heterogeneous integration III-V on silicon
→ wafer-scale laser integration



The Heterogeneous Technology Alliance HTA

Germanium photo-detectors on silicon



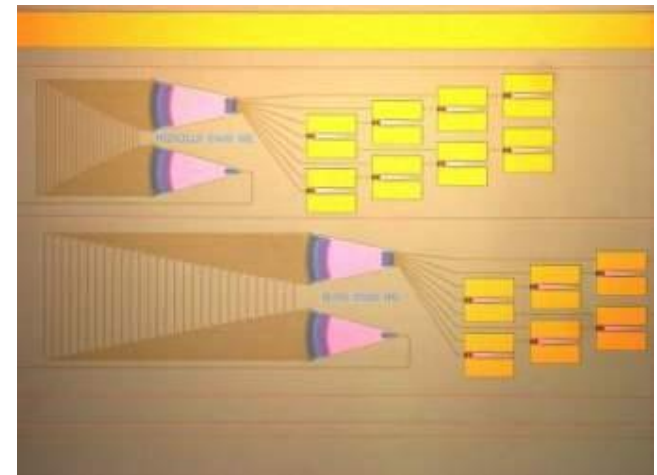
Median dark current:

< 180nA @-2V

< 25nA @-0.5V

Responsivity @1550nm 0.8 A/W

40GHz BW @0V bias



Integration with SOI waveguides



leti



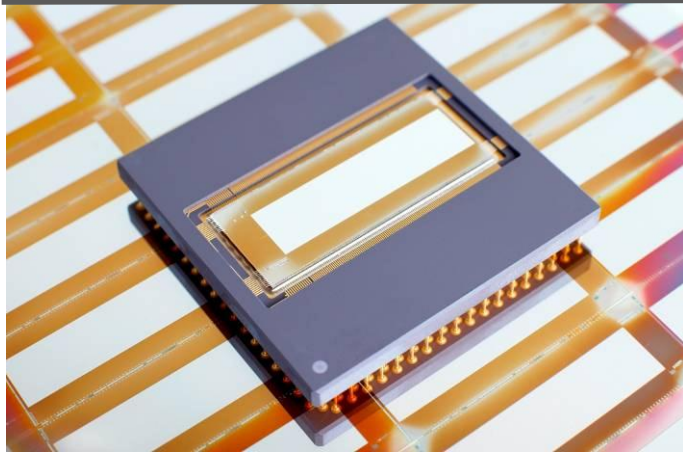
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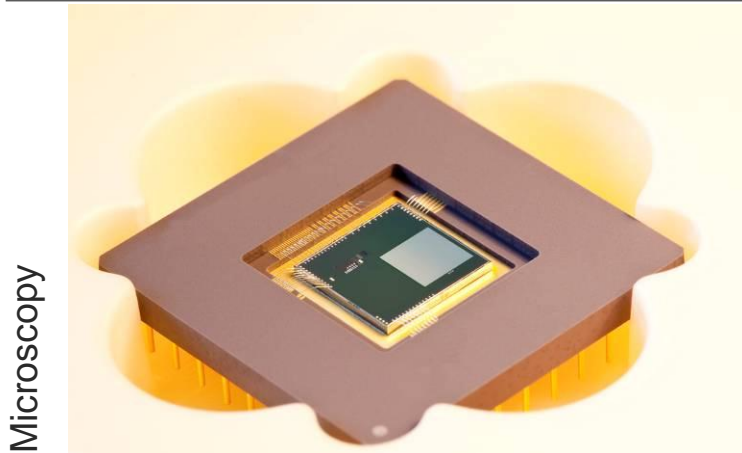
Fraunhofer
MIKROELEKTRONIK

Micro mirror arrays

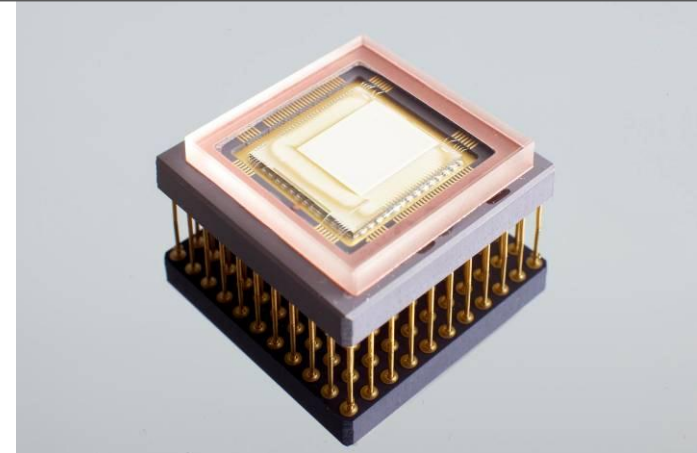


Programmable masks

Direct Imaging



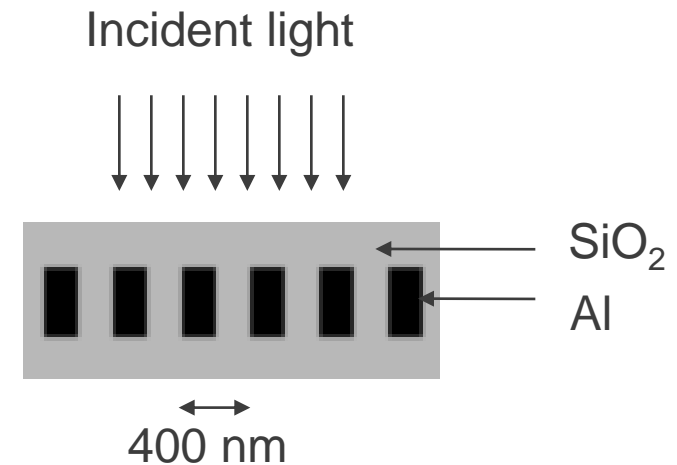
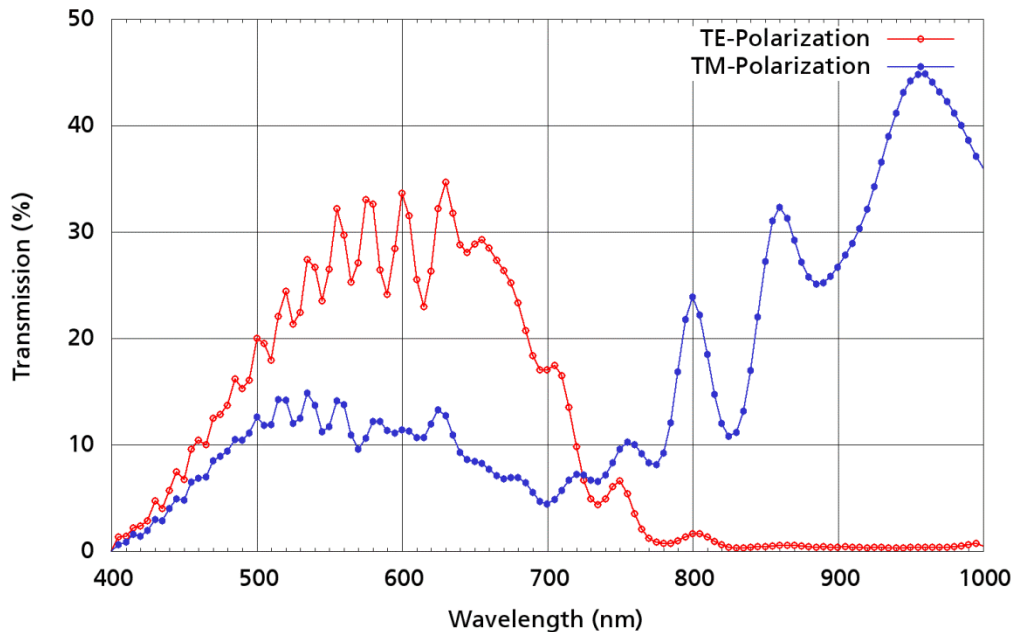
Microscopy



Adaptive Optics

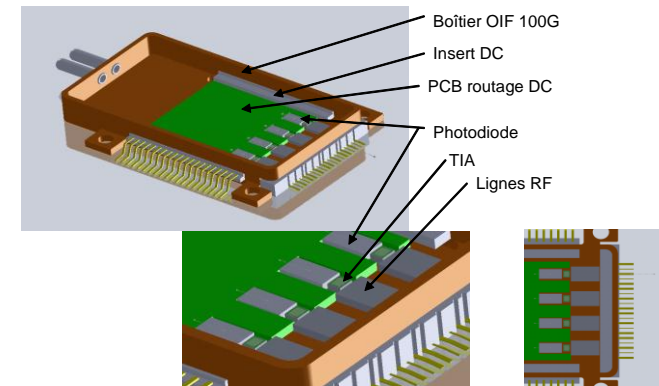
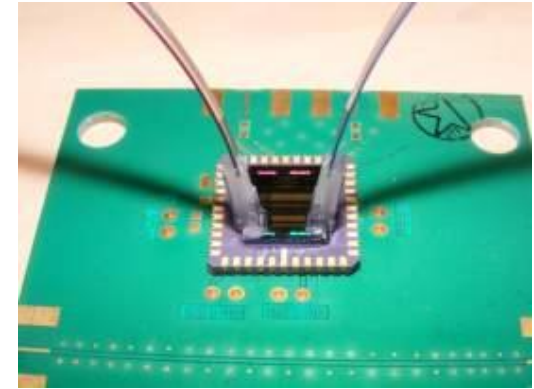
Nanostructured optical filters in CMOS: Polarization filters

- Wire gratings fabricated in CMOS technology
 - Good polarization sensitivity
 - Contrast ratio > 50:1 at 850 nm
 - Low attenuation of filters

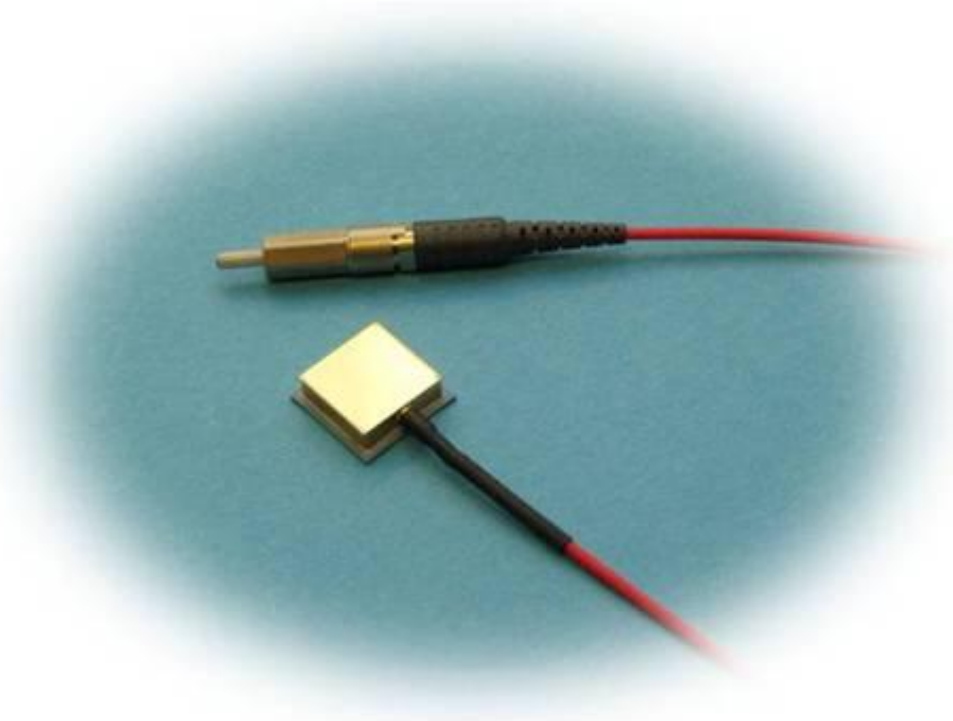


The Heterogeneous Technology Alliance HTA Packaging and module integration

- Fiber Pigtailling
 - Active alignment (multichannel)
 - Vision assisted alignment
 - Passive alignment
- Electronics Hybrid Integration
 - Multi Chip Module (wire bonding)
 - System In Package (flip-chip)
 - Copper Pillar
 - Other
- Optical 2D/3D Interconnects (Interposers)



- Shock 3000 g
- Random vibration 25 grms
- Vacuum
- Radiation 1000 Gy (gamma, protons, ions)
- Temp: operation -40...+85 °C, storage -55...+125°C
- Hermeticity verified: 500 cycles - 55...+125°C
- Space-grade fibre cable and connector



The Heterogeneous Technology Alliance HTA

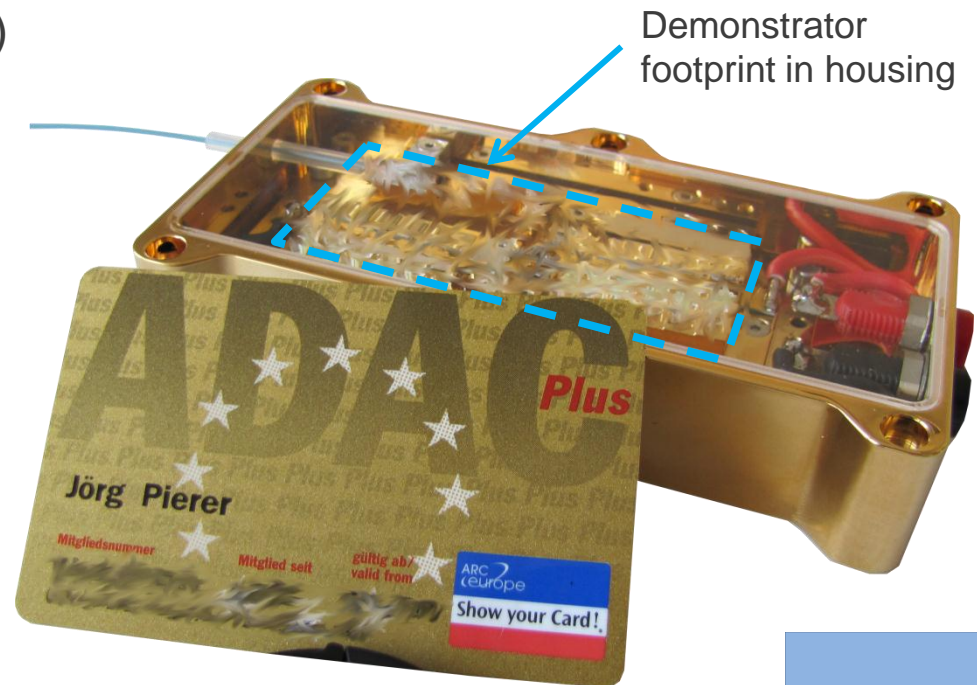
High power single emitter laser diode modules



- optical powers > 100 W
- highly repeatable processes
- very fast assembly (more than 40 optical components in less than 2 hours)
- easy process adaptation to
 - different product lines
 - miniaturized modules



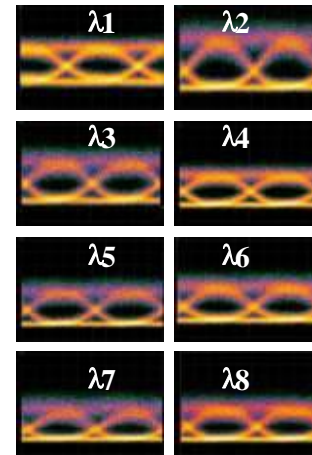
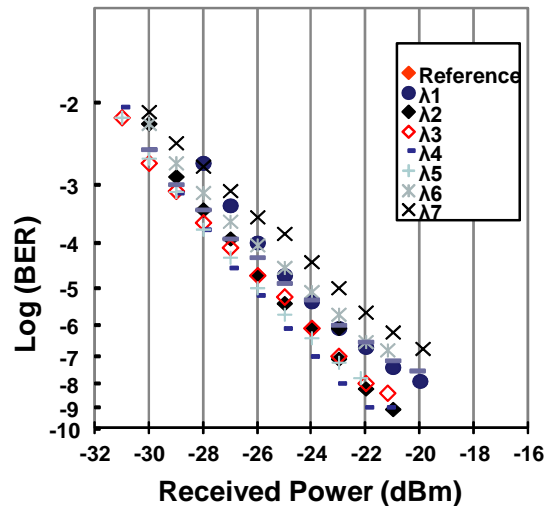
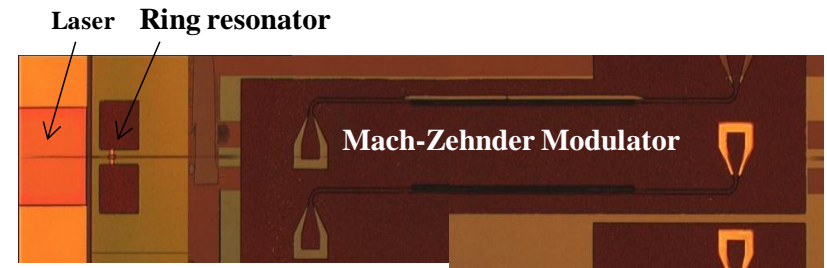
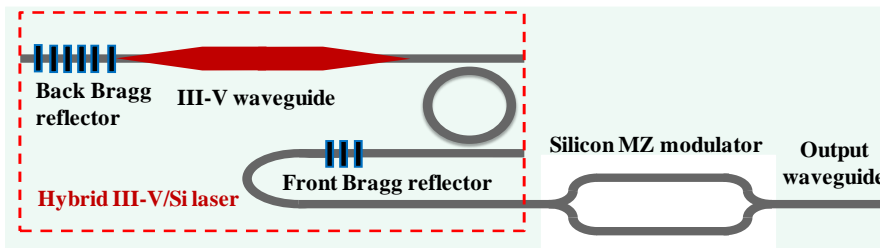
- high yield rates
- reliable products



DDP 100

From components to circuits: Integrated tunable transmitter

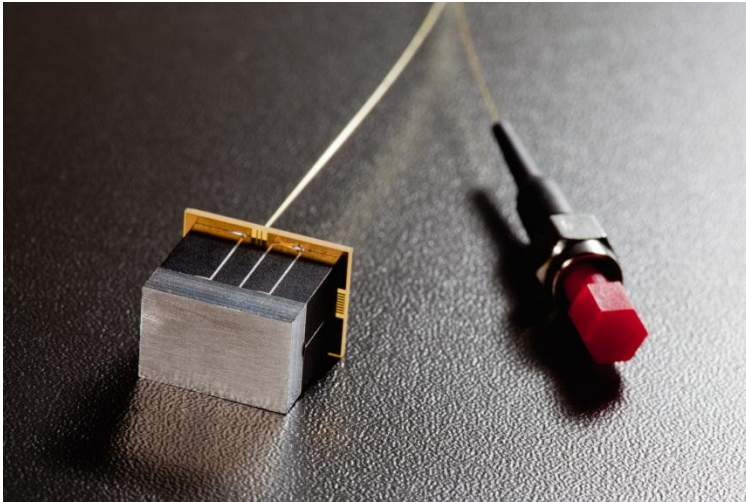
- hybrid III-V/Si laser + silicon Mach-Zehnder modulator
- 8 nm tunability



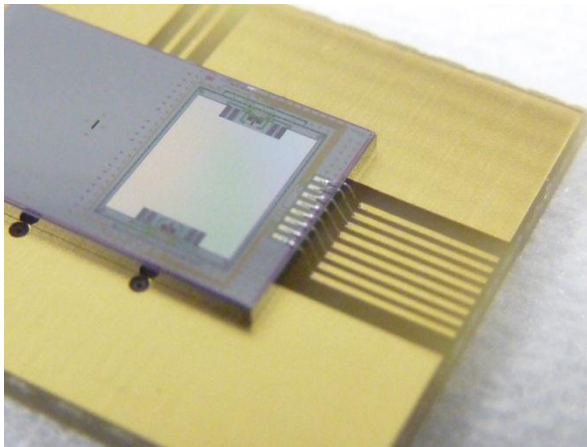
Excellent BER performance at 10Gb/s

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Miniaturized NIR Spectrometer

Application example: food quality



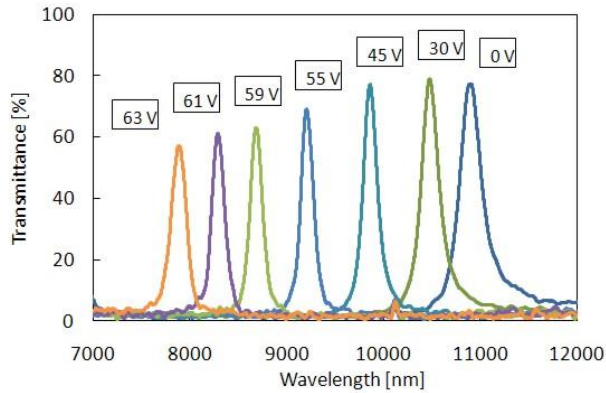
Micro spectrometer Size: 2cm³



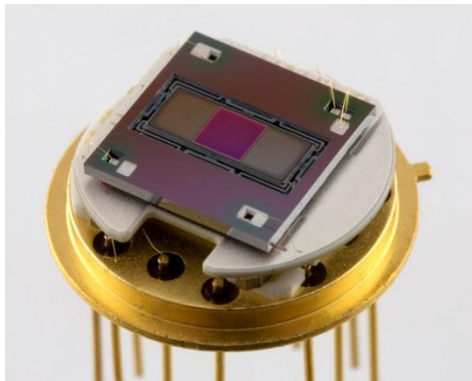
Scanning grating chip



The Heterogeneous Technology Alliance HTA Interferometer and spectrometers



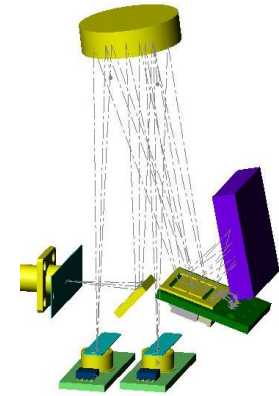
Transmittance vs. drive voltage



FPI and pyroelectric detector (courtesy of InfraTec GmbH Dresden)

Fabry-Pérot-
Inteferometer

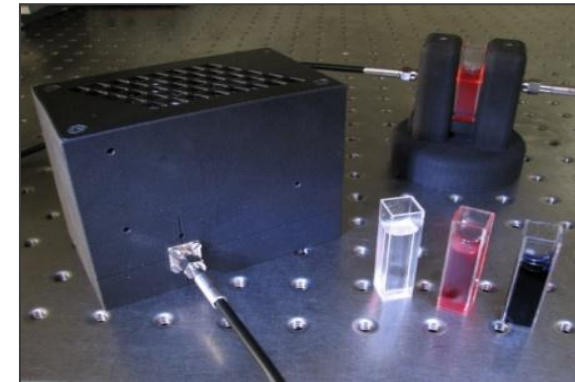
Micro-Mirror
Spectrometer



Optical scheme of the spectrometer

Benefits:
-Spectral range 0.6 – 11 μm

Applications:
- Gas analysis
- Safety systems
- Analysis of fluids



MOEMS spectrometer

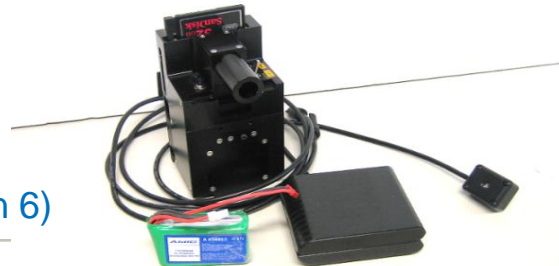
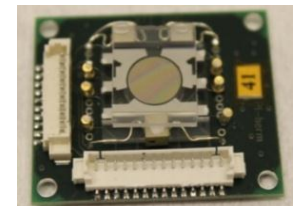
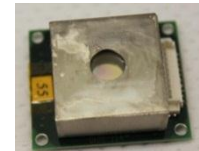
- **MEMS Fabry-Perot Interferometer**

- For high volumes (>10'000/a)
- Small, robust, inexpensive, batch-producible



- **PIEZO-actuated Fabry Perot Interferometer**

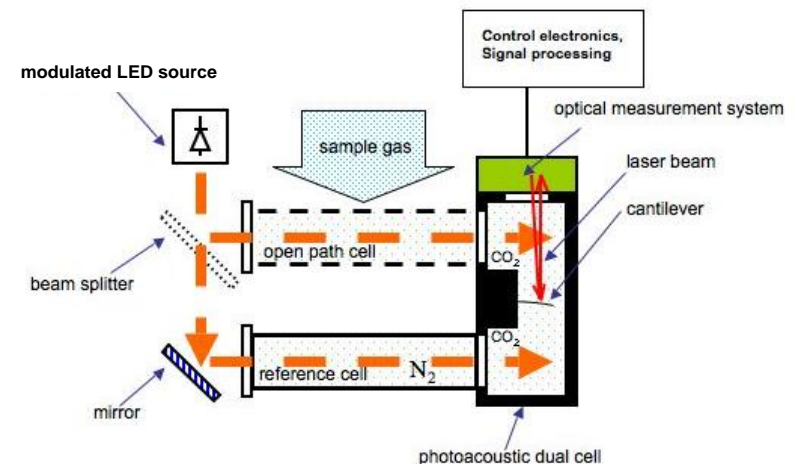
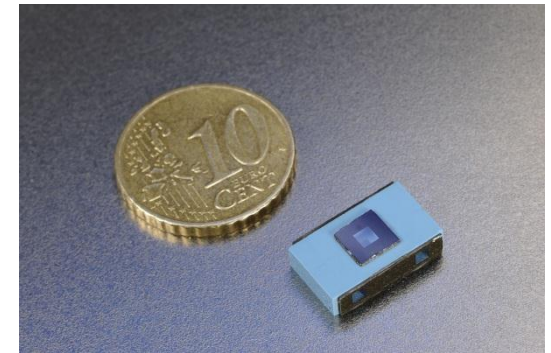
- Especially for imaging and multipoint applications
- Assembled 'one-by-one'
- For small to medium volumes (10 – 1'000 /a)



More details: [October 16, 2012 at 17:10 \(Session 6\)](#)

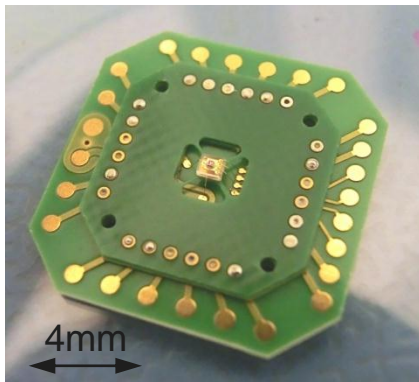
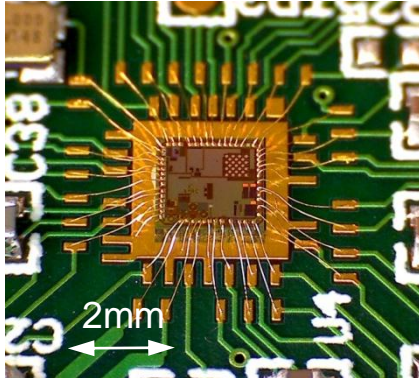
Miniaturized photoacoustic gas sensor based on patented interferometric readout and novel photonic integration technologies

- Photoacoustic gas sensor with a volume of less than 5 cm^3
- Two or three orders of magnitude better sensitivity than other methods
- Based on the use of a MEMS cantilever microphone.
- VTT (coordin.), QinetiQ (UK), Ioffe (RUS), University of Turku (FI), Gasera (FI), Doble (NO), Selex (IT)



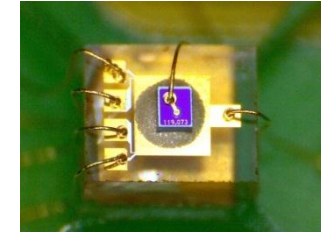
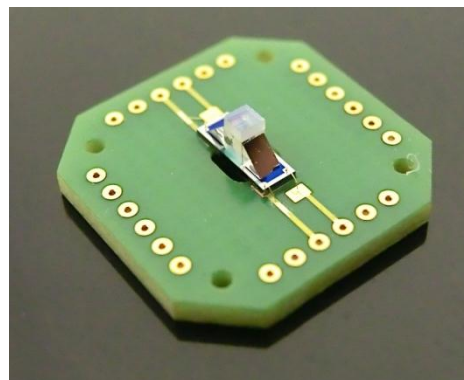
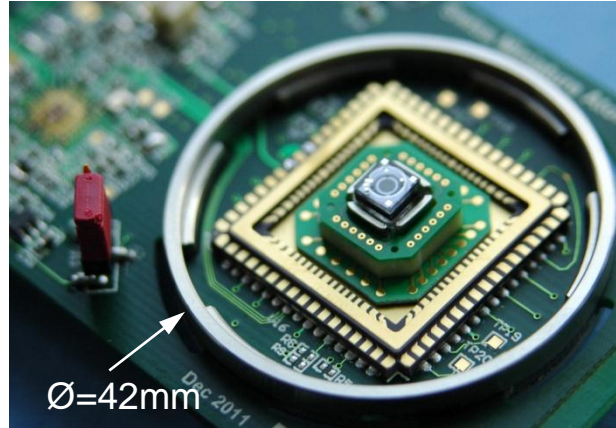
SMAC – Swiss Miniature Atomic Clock

ASIC

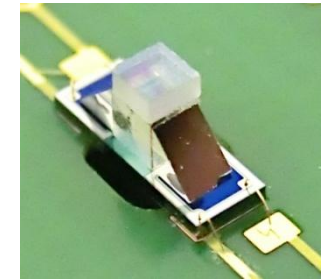


csem

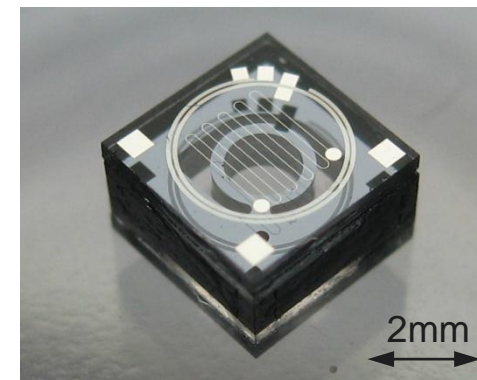
SMAC



Laser



Optics



Cell

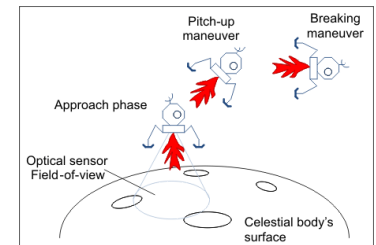
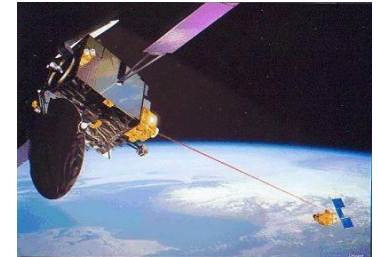
More details: Wednesday, October 17, 2012 at 16:20 (Session 10)

Applications are manifold including

- Image sensing
- Biosensing
- 3D measurements of components and objects
- Fiber-optic sensors for harsh environment and medical applications
- Medical diagnostics
- High-power lasers for marking, cutting and welding
- Industrial process control
- **Space (shock, vibration, vacuum, radiation, temperature, hermeticity)**

Applications including

- Optical communication: Intersatellite laser communication, (mobile) optical ground stations, optical receivers, pointing, acquisition, tracking, ...
- 3D time-of-flight for space (e.g. Mars Sample Return Mission):
 - Precise entry, descent and (soft-) landing
 - Rendezvous/docking in orbit (sample canister with orbiter)
 - Structure deployment monitoring (e.g. PV panels)
 - Rover navigation.
- Spectroscopy: ChemCam (NASA) measures chemical rock content on MARS optically
- ...



The HTA Photonic Sensing and Integration Platform

The platform will provide many opportunities and solutions for the European photonics market including

- the development of robust, reliable and low cost processes designed for devices/sensors and complete photonic systems
- precision robot systems for automation,
- manufacturing capabilities through the build up an extension of an infrastructure for process development and pilot and small series.

Key devices such as Silicon MEMS and high-brightness light sources will be combined with 3D integration technologies to allow flexible manufacturing.

The Heterogeneous Technology Alliance HTA
Made in Europe



